

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00569	0.66	0.09702
	Doped silicon	Silicon (Si)	7440-21-3	0.85577	99.34	14.60298
		Subtotal		0.86146	100	14.7
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01547	5.0	0.26403
	Silver alloy	Silver (Ag)	7440-22-4	0.00464	1.5	0.07921
	Lead alloy	Lead (Pb)	7439-92-1	0.28934	93.5	4.93735
		Subtotal		0.30945	100	5.28059
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.47844	100.0	8.16423
		Subtotal		0.47844	100	8.16423
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.06458	0.1	1.102
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01937	0.03	0.3306
	Copper alloy	Copper (Cu)	7440-50-8	64.49589	99.87	1100.5674
		Subtotal		64.57984	100	1102
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.13303	100.0	2.27
		Subtotal		0.13303	100	2.27
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.5137	4.5	25.83
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.36378	10.0	57.4
	Filler	Silica fused	60676-86-0	25.22833	75.0	430.5
	Metal hydroxide	Metal hydroxide		3.36378	10.0	57.4
	Carbon Black	Carbon black	1333-86-4	0.16819	0.5	2.87
		Subtotal		33.63778	100	574
		Total		100	100	1706.41482

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